

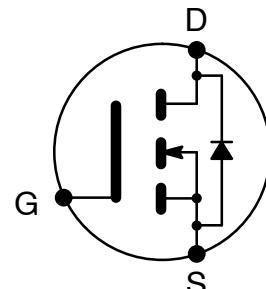


ELECTRONICS, INC.  
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**NTE2922  
MOSFET  
N-Ch, Enhancement Mode  
High Speed Switch  
TO3P Type Package**

**Features:**

- Dynamic dv/dt Rating
- Repetitive Avalanche Rated
- Isolated Central Mounting Hole
- Fast Switching
- Ease of Parallelizing
- Simple Drive Requirements



**Absolute Maximum Ratings:**

Continuous Drain Current ( $V_{GS} = 10V$ ), $I_D$	
$T_C = +25^\circ C$ .....	16A
$T_C = +100^\circ C$ .....	10A
Pulsed Drain Current (Note 1), $I_{DM}$ .....	64A
Power Dissipation ( $T_C = +25^\circ C$ ), $P_D$ .....	180W
Gate-to-Source Voltage, $V_{GS}$ .....	$\pm 20$
Single Pulse Avalanche Energy (Note 2), $E_{AS}$ .....	390mJ
Avalanche Current (Note 1), $I_{AR}$ .....	16A
Repetitive Avalanche Energy (Note 1), $E_{AR}$ .....	19mJ
Peak Diode Recovery dv/dt (Note 3), dv/dt .....	4V/ns
Operating Junction Temperature Range, $T_J$ .....	-55° to +150°C
Storage Temperature Range, $T_{stg}$ .....	-55° to +150°C
Lead Temperature (During Soldering, 1.6mm from case for 10sec), $T_L$ .....	+300°C
Thermal Resistance, Junction-to-Case, $R_{thJC}$ .....	0.7°C/W
Thermal Resistance, Junction-to-Ambient, $R_{thJA}$ .....	30°C/W

Note 1. Repetitive rating; pulse width limited by maximum junction temperature.

Note 2.  $V_{DD} = 50V$ , starting  $T_J = +25^\circ C$ ,  $L = 2.7mH$ ,  $R_G = 25\Omega$ ,  $I_{AS} = 16A$

Note 3.  $I_{SD} \leq 16A$ ,  $di/dt \leq 200A/\mu s$ ,  $V_{DD} \leq 400V$ ,  $T_J \leq +150^\circ C$

**Electrical Characteristics:** ( $T_J = +25^\circ\text{C}$  unless otherwise specified)

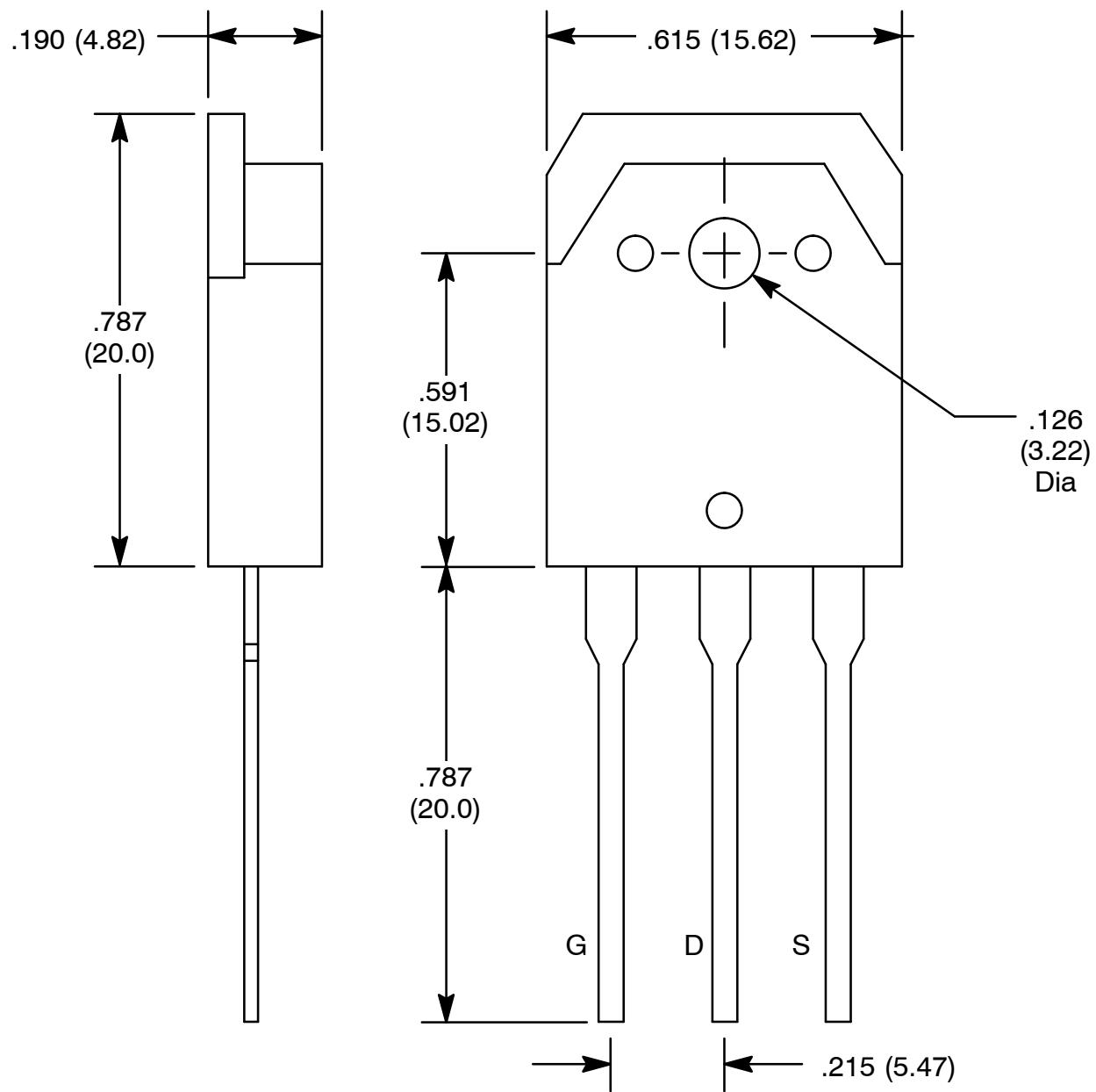
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-to-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	400	—	—	V
Breakdown Voltage Temp. Coefficient	$\frac{\Delta V_{(\text{BR})\text{DSS}}}{\Delta T_J}$	Reference to $+25^\circ\text{C}$ , $I_D = 1\text{mA}$	—	0.51	—	$\text{V}/^\circ\text{C}$
Static Drain-to-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 8.9\text{A}$	—	—	0.30	$\Omega$
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	2.0	—	4.0	V
Forward Transconductance	$g_{\text{fs}}$	$V_{\text{DS}} = 40\text{V}, I_D = 8\text{A}$	8	—	—	S
Drain-to-Source Leakage Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 400\text{V}, V_{\text{GS}} = 0\text{V}$	—	—	25	$\mu\text{A}$
Gate-to-Source Forward Leakage	$I_{\text{GSS}}$	$V_{\text{GS}} = 20\text{V}, V_{\text{DS}} = 0$	—	—	100	nA
Gate-to-Source Reverse Leakage	$I_{\text{GSR}}$	$V_{\text{GS}} = -20\text{V}, V_{\text{DS}} = 0$	—	—	-100	nA
Total Gate Charge	$Q_g$	$I_D = 16\text{A}, V_{\text{DS}} = 320\text{V}, V_{\text{GS}} = 10\text{V}$ , Note 4	—	—	150	nC
Gate-to-Source Charge	$Q_{\text{gs}}$		—	—	23	nC
Gate-to-Drain ("Miller") Charge	$Q_{\text{gd}}$		—	—	80	nC
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 200\text{V}, I_D = 16\text{A}, R_G = 6.2\Omega$ , $R_D = 12\Omega$ , Note 4	—	16	—	ns
Rise Time	$t_r$		—	49	—	ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		—	87	—	ns
Fall Time	$t_f$		—	47	—	ns
Internal Drain Inductance	$L_D$	Between lead, .250in. (6.0) mm from package and center of die contact	—	5.0	—	nH
Internal Source Inductance	$L_S$		—	13	—	nH
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 25\text{V}, f = 1\text{MHz}$	—	2600	—	pF
Output Capacitance	$C_{\text{oss}}$		—	660	—	pF
Reverse Transfer Capacitance	$C_{\text{rss}}$		—	250	—	pF

**Source-Drain Ratings and Characteristics:**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Continuous Source Current (Body Diode)	$I_S$		—	—	16	A
Pulsed Source Current (Body Diode)	$I_{\text{SM}}$	Note 1	—	—	64	A
Diode Forward Voltage	$V_{\text{SD}}$	$T_J = +25^\circ\text{C}, I_S = 16\text{A}, V_{\text{GS}} = 0\text{V}$	—	—	1.6	V
Reverse Recovery Time	$t_{\text{rr}}$	$T_J = +25^\circ\text{C}, I_F = 16\text{A}$ , $dI/dt = 100\text{A}/\mu\text{s}$ , Note 4	—	380	570	ns
Reverse Recovery Charge	$Q_{\text{rr}}$		—	4.7	7.1	$\mu\text{C}$
Forward Turn-On Time	$t_{\text{on}}$	Intrinsic turn-on time is negligible (turn-on is dominated by $L_S+L_D$ )				

Note 1. Repetitive rating; pulse width limited by maximum junction temperature.

Note 4. Pulse width  $\leq 300\mu\text{s}$ ; duty cycle  $\leq 2\%$ .



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